

Features

- Trench FET Structure
- High Dense Cell Design for Extremely Low $R_{DS(ON)}$
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free. "Green" Device (Note 1)
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)
- Moisture Sensitivity Level 1

Dual N&P-Channel MOSFET

Maximum Ratings

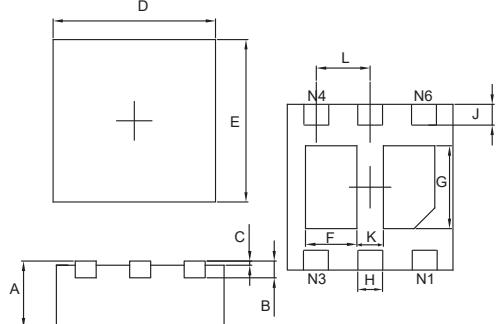
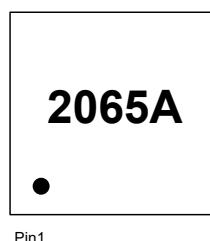
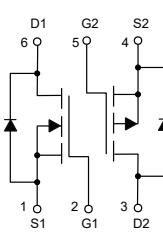
- Operating Junction Temperature Range: -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Typical Thermal Resistance: 62.5°C/W Junction to Ambient (Note 2)

Parameter	Symbol	Rating	Unit
N-Channel			
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 10	V
Continuous Drain Current	I_D	6	A
$T_A=70^\circ\text{C}$		4.8	
Pulsed Drain Current	I_{DM}	20	A
Total Power Dissipation	P_D	2	W
P-Channel			
Drain-Source Voltage	V_{DS}	-20	V
Gate-Source Voltage	V_{GS}	± 10	V
Continuous Drain Current	I_D	-4	A
$T_A=25^\circ\text{C}$		-3.2	
Pulsed Drain Current	I_{DM}	-16	A
Total Power Dissipation	P_D	2	W

Note: 1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

2. Surface Mounted on 1 square inch of 2oz copper for FR4 Board.

Internal Structure and Marking Code



DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	0.030	0.034	0.750	0.850	
B	0.008		0.200		TYP.
C	0.000	0.002	0.000	0.050	
D	0.077	0.081	1.950	2.050	
E	0.077	0.081	1.950	2.050	
F	0.017	0.027	0.440	0.690	
G	0.033	0.043	0.840	1.090	
H	0.010	0.014	0.250	0.350	
J	0.007	0.015	0.175	0.375	
K	0.010	0.014	0.250	0.350	
L	0.026		0.650		TYP.

N-MOSFET ELECTRICAL CHARACTERISTICS (Ta=25°C unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =250μA	20			V
Gate-Source Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±10V			±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =20V, V _{GS} =0V			1	μA
Gate-Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	0.4	0.6	1.0	V
Drain-Source On-Resistance ^(Note3)	R _{DS(on)}	V _{GS} =4.5V, I _D =5A		20	25	mΩ
		V _{GS} =2.5V, I _D =4A		25	32	mΩ
		V _{GS} =1.8V, I _D =2A		33	49	mΩ
Diode Characteristics						
Diode Forward Voltage ^(Note3)	V _{SD}	V _{GS} =0V, I _S =5A			1.2	V
Reverse Recovery Time	t _{rr}	I _{SD} =4.5 A, dI _{SD} /dt=100A/μs		17.9		nS
Reverse Recovery Charge	Q _{rr}			1.38		nC
Dynamic Characteristics ^(Note4)						
Input Capacitance	C _{iss}	V _{DS} =10V, V _{GS} =0V, f=1MHz		418		pF
Output Capacitance	C _{oss}			82		
Reverse Transfer Capacitance	C _{rss}			70		
Total Gate Charge	Q _g	V _{GS} =4.5V, V _{DS} =10V, I _D =4.5A		7.65		nC
Gate-Source Charge	Q _{gs}			1.16		
Gate-Drain Charge	Q _{gd}			1.89		
Turn-On Delay Time	t _{d(on)}	V _{GS} =4.5V, V _{DS} =10V, R _{GEN} =6Ω, I _D =1A		6.5		ns
Turn-On Rise Time	t _r			21		
Turn-Off Delay Time	t _{d(off)}			28.4		
Turn-Off Fall Time	t _f			26.3		

P-MOSFET ELECTRICAL CHARACTERISTICS ($T_a=25^\circ\text{C}$ unless otherwise specified)

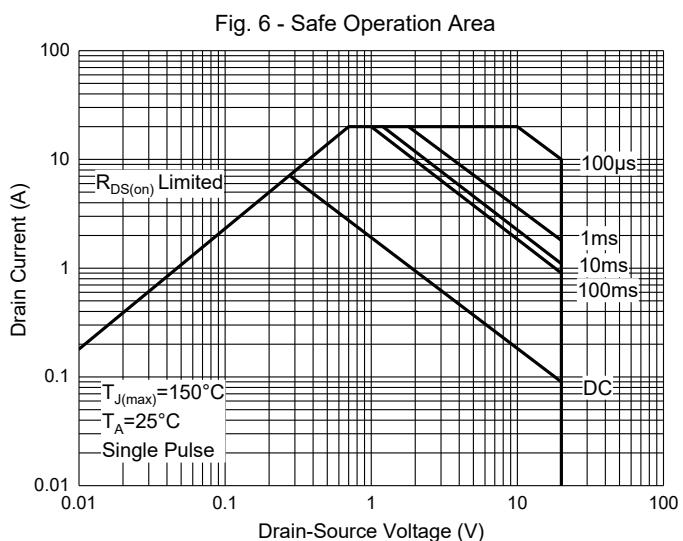
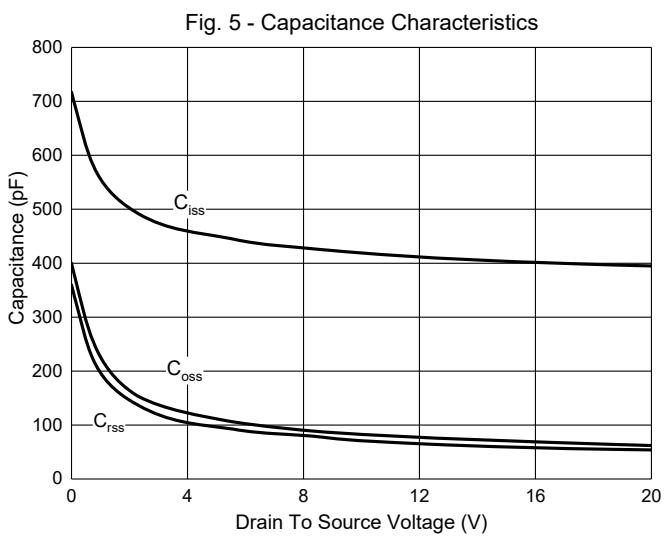
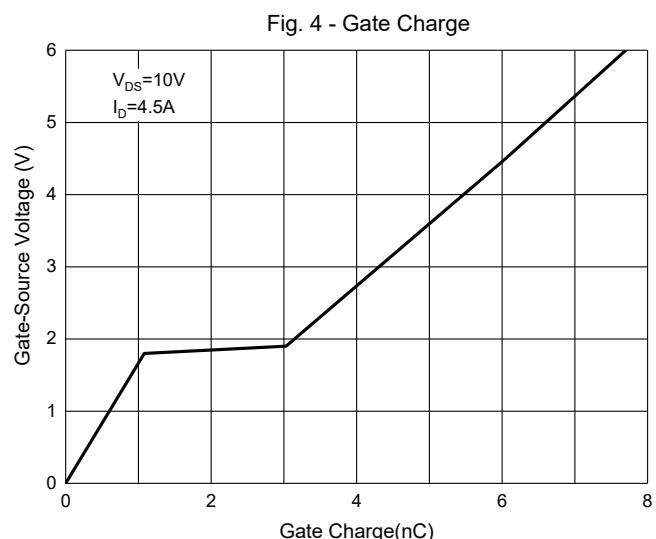
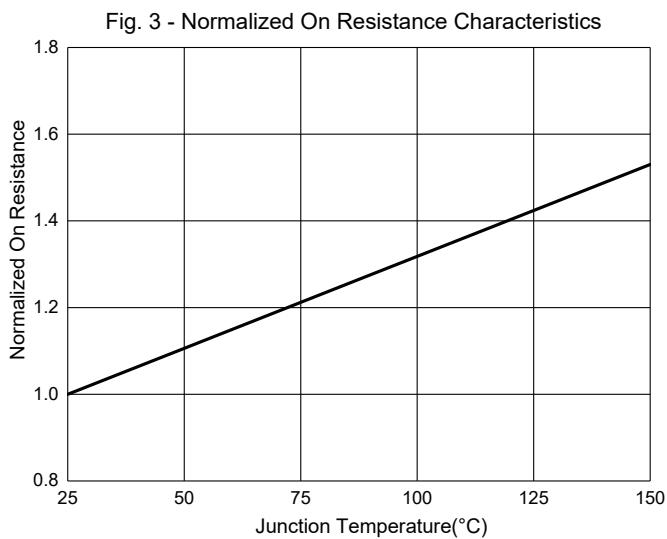
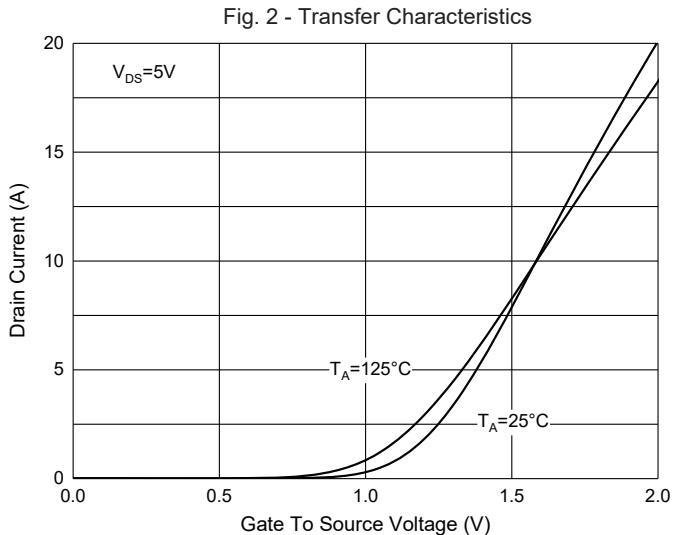
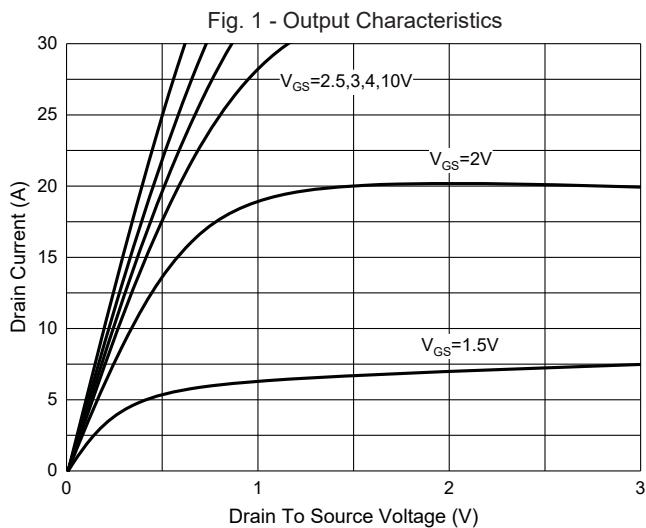
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS}=0\text{V}, I_D=-250\mu\text{A}$	-20			V
Gate-Source Leakage Current	I_{GSS}	$V_{DS}=0\text{V}, V_{GS} = \pm 10\text{V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-20\text{V}, V_{GS}=0\text{V}$			-1	μA
Gate-Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS}=V_{GS}, I_D=-250\mu\text{A}$	-0.4	-0.7	-1	V
Drain-Source On-Resistance ^(Note3)	$R_{DS(\text{on})}$	$V_{GS}=-4.5\text{V}, I_D=-3.4\text{A}$		44	51	$\text{m}\Omega$
		$V_{GS}=-2.5\text{V}, I_D=-3\text{A}$		60	67	$\text{m}\Omega$
		$V_{GS}=-1.8\text{V}, I_D=-2.5\text{A}$		94	100	$\text{m}\Omega$
Diode Characteristics						
Diode Forward Voltage ^(Note3)	V_{SD}	$V_{GS}=0\text{V}, I_S=-3.4\text{A}$			-1.2	V
Reverse Recovery Time	t_{rr}	$I_{SD}=-3.7\text{A}, dI_{SD}/dt=100\text{A}/\mu\text{s}$		24.5		nS
Reverse Recovery Charge	Q_{rr}			4		nC
Dynamic Characteristics ^(Note4)						
Input Capacitance	C_{iss}	$V_{DS}=-6\text{V}, V_{GS}=0\text{V}, f=1\text{MHz}$		880		pF
Output Capacitance	C_{oss}			270		
Reverse Transfer Capacitance	C_{rss}			175		
Total Gate Charge	Q_g	$V_{GS}=-10\text{V}, V_{DS}=-10\text{V}, I_D=-3.7\text{A}$		5.41		nC
Gate-Source Charge	Q_{gs}			1.17		
Gate-Drain Charge	Q_{gd}			1.24		
Turn-On Delay Time	$t_{d(on)}$	$V_{GS}=-4.5\text{V}, V_{DS}=-10\text{V}$, $R_{\text{GEN}}=6\Omega, I_D=-1\text{A}$		7		ns
Turn-On Rise Time	t_r			21.4		
Turn-Off Delay Time	$t_{d(off)}$			46		
Turn-Off Fall Time	t_f			34.8		

Notes:

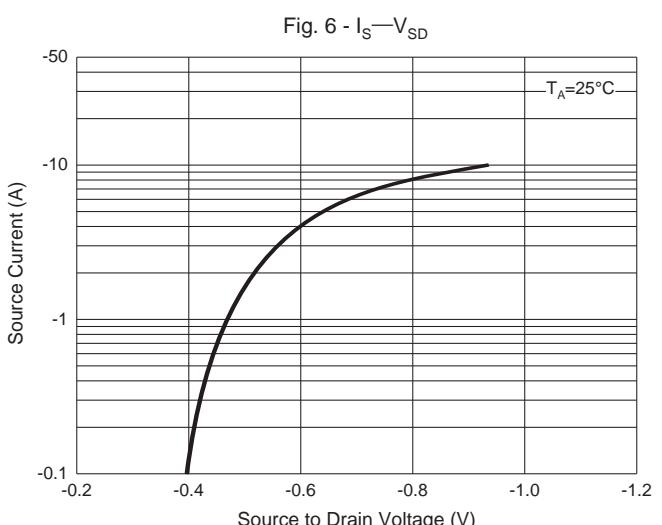
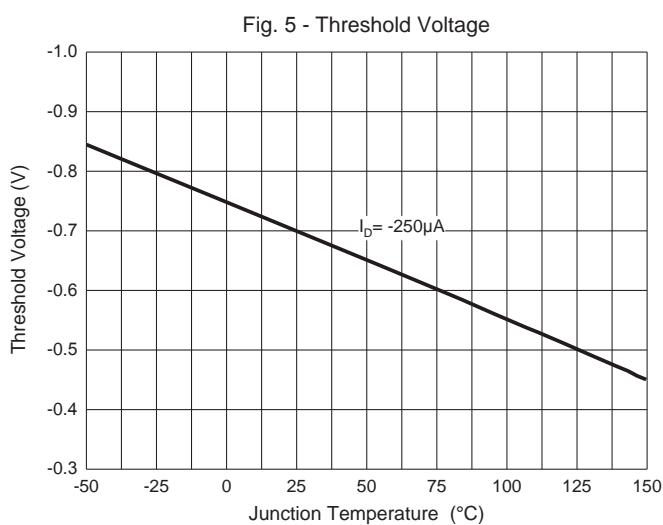
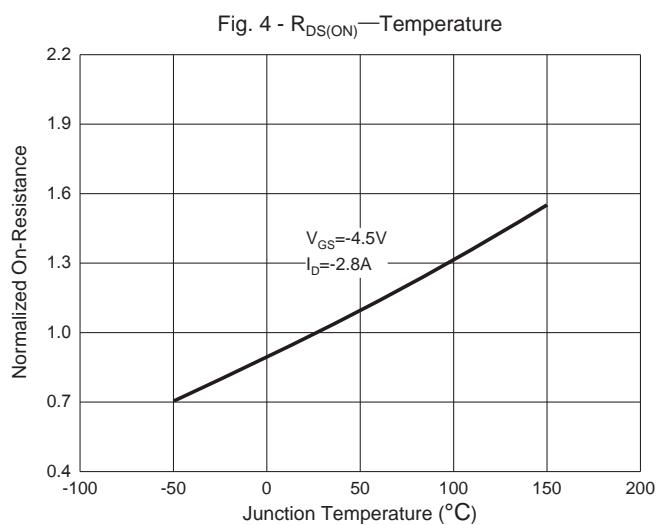
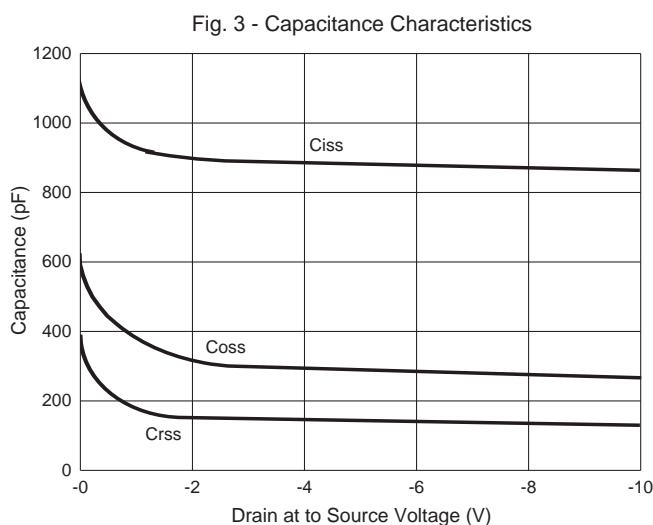
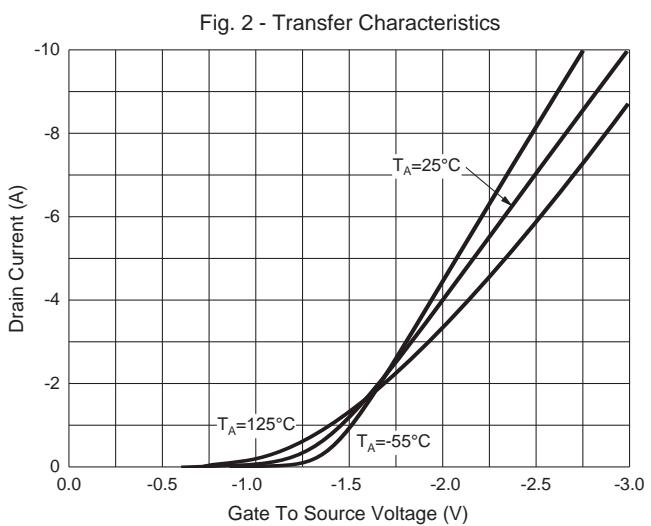
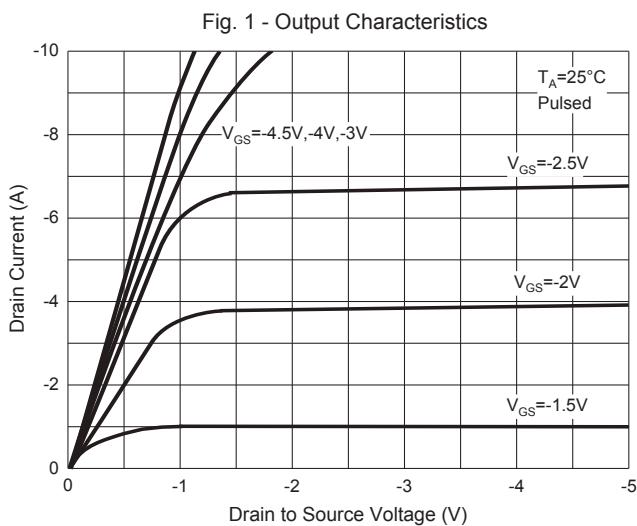
3. Pulse Test: Pulse Width $\leq 300\mu\text{A}$, Duty Cycle $\leq 2\%$.

4. Guaranteed by Design, Not Subject to Production Testing.

N-MOSFET Curve Characteristics



Curve Characteristics



Ordering Information

Device	Packing
Part Number-TP	Tape&Reel:3Kpcs/Reel

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